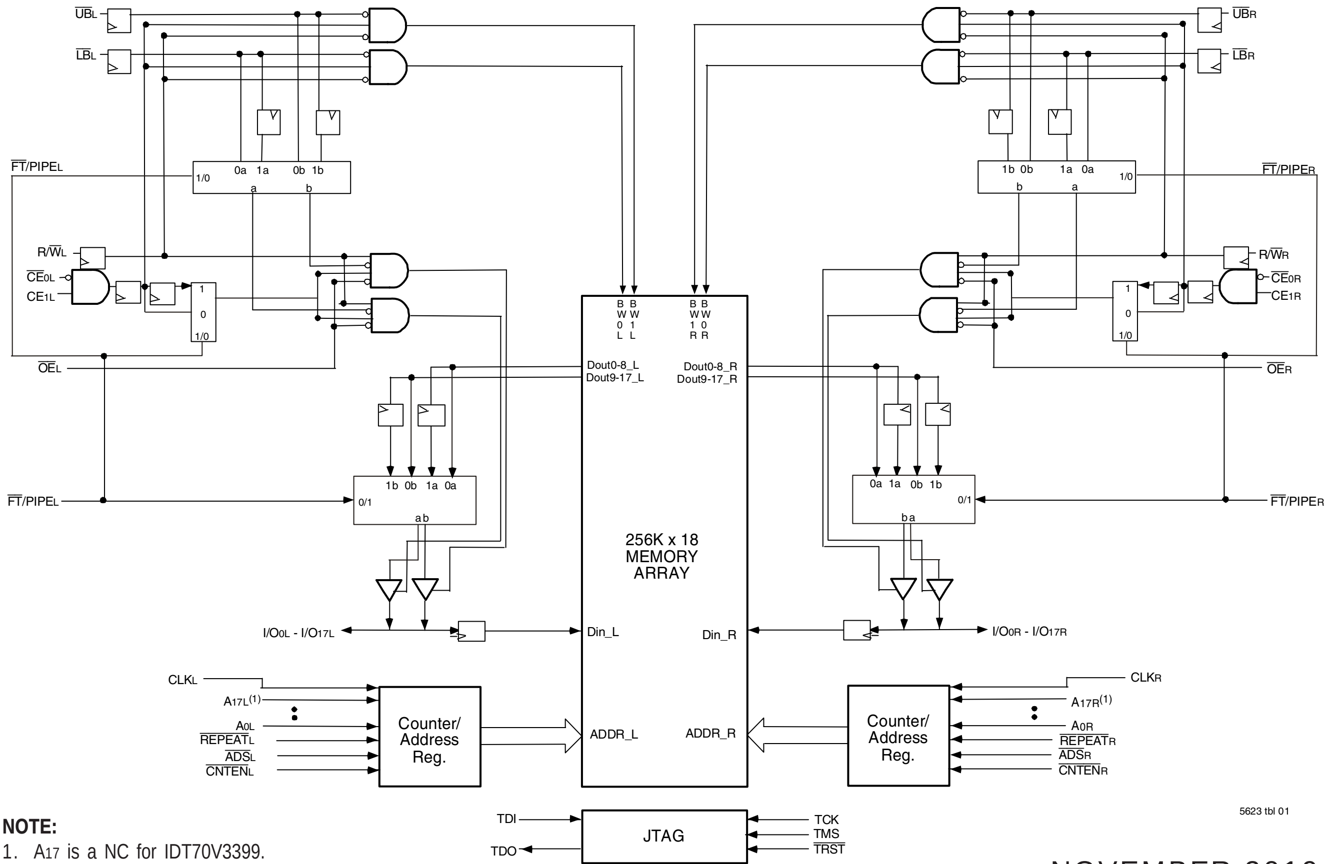
HIGH-SPEED 3.3V 256/128K x 18 SYNCHRONOUS DUAL-PORT STATIC RAM WITH 3.3V OR 2.5V INTERFACE

70V3319/99S

Features:

- **True Dual-Port memory cells which allow simultaneous access of the same memory location**
- **High-speed data access**
  - *Commercial: 3.6ns (166MHz)/4.2ns (133MHz) (max.)*
  - *Industrial: 4.2ns (133MHz) (max.)*
- **Selectable Pipelined or Flow-Through output mode**
  - *Due to limited pin count PL/$\overline{FT}$ option is not supported on the 128-pin TQFP package. Device is pipelined outputs only on each port.*
- **Counter enable and repeat features**
- **Dual chip enables allow for depth expansion without additional logic**
- **Full synchronous operation on both ports**
  - *6ns cycle time, 166MHz operation (6Gbps bandwidth)*
  - *Fast 3.6ns clock to data out*
  - *1.7ns setup to clock and 0.5ns hold on all control, data, and address inputs @ 166MHz*
  - *Data input, address, byte enable and control registers*
  - *Self-timed write allows fast cycle time*
- **Separate byte controls for multiplexed bus and bus matching compatibility**
- **Dual Cycle Deselect (DCD) for Pipelined Output mode**
- **LVTTL- compatible, single 3.3V (±150mV) power supply for core**
- **LVTTL compatible, selectable 3.3V (±150mV) or 2.5V (±100mV) power supply for I/Os and control signals on each port**
- **Industrial temperature range (-40°C to +85°C) is available at 133MHz.**
- **Available in a 128-pin Thin Quad Flatpack, 208-pin fine pitch Ball Grid Array, and 256-pin Ball Grid Array**
- **Supports JTAG features compliant to IEEE 1149.1**
  - *Due to limited pin count, JTAG is not supported on the 128-pin TQFP package*
- **Green parts available, see ordering information**

Functional Block Diagram



NOTE:

1. A_{17} is a NC for IDT70V3399.

NOVEMBER 2019

Description:

The IDT70V3319/99 is a high-speed 256/128K x 18 bit synchronous Dual-Port RAM. The memory array utilizes Dual-Port memory cells to allow simultaneous access of any address from both ports. Registers on control, data, and address inputs provide minimal setup and hold times. The timing latitude provided by this approach allows systems to be designed with very short cycle times. With an input data register, the IDT70V3319/99 has been optimized for applications having unidirectional or bidirectional data flow in bursts. An automatic power down feature, controlled by $\overline{\text{CE}}_0$ and CE$_1$, permits the on-chip circuitry of each port to enter a very low standby power mode.

The 70V3319/99 can support an operating voltage of either 3.3V or 2.5V on one or both ports, controllable by the OPT pins. The power supply for the core of the device (V$_{DD}$) remains at 3.3V.

Pin Configuration(1,2,3,4,5)

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	
I/O$_{9L}$	NC	V$_{SS}$	TDO	NC	A$_{16L}$	A$_{12L}$	A$_{8L}$	NC	V$_{DD}$	CLK$_L$	$\overline{\text{CNTEN}}_L$	A$_{4L}$	A$_{0L}$	OPT$_L$	NC	V$_{SS}$	A
NC	V$_{SS}$	NC	TDI	A$_{17L}$(1)	A$_{13L}$	A$_{9L}$	NC	$\overline{\text{CE}}_{0L}$	V$_{SS}$	$\overline{\text{ADS}}_L$	A$_{5L}$	A$_{1L}$	V$_{SS}$	V$_{DDQR}$	I/O$_{8L}$	NC	B
V$_{DDQL}$	I/O$_{9R}$	V$_{DDQR}$	PIPE/$\overline{\text{FT}}_L$	NC	A$_{14L}$	A$_{10L}$	$\overline{\text{UB}}_L$	CE$_{1L}$	V$_{SS}$	R/$\overline{\text{W}}_L$	A$_{6L}$	A$_{2L}$	V$_{DD}$	I/O$_{8R}$	NC	V$_{SS}$	C
NC	V$_{SS}$	I/O$_{10L}$	NC	A$_{15L}$	A$_{11L}$	A$_{7L}$	$\overline{\text{LB}}_L$	V$_{DD}$	$\overline{\text{OE}}_L$	$\overline{\text{REPEAT}}_L$	A$_{3L}$	V$_{DD}$	NC	V$_{DDQL}$	I/O$_{7L}$	I/O$_{7R}$	D
I/O$_{11L}$	NC	V$_{DDQR}$	I/O$_{10R}$										I/O$_{6L}$	NC	V$_{SS}$	NC	E
V$_{DDQL}$	I/O$_{11R}$	NC	V$_{SS}$										V$_{SS}$	I/O$_{6R}$	NC	V$_{DDQR}$	F
NC	V$_{SS}$	I/O$_{12L}$	NC										NC	V$_{DDQL}$	I/O$_{5L}$	NC	G
V$_{DD}$	NC	V$_{DDQR}$	I/O$_{12R}$										V$_{DD}$	NC	V$_{SS}$	I/O$_{5R}$	H
V$_{DDQL}$	V$_{DD}$	V$_{SS}$	V$_{SS}$										V$_{SS}$	V$_{DD}$	V$_{SS}$	V$_{DDQR}$	J
I/O$_{14R}$	V$_{SS}$	I/O$_{13R}$	V$_{SS}$										I/O$_{3R}$	V$_{DDQL}$	I/O$_{4R}$	V$_{SS}$	K
NC	I/O$_{14L}$	V$_{DDQR}$	I/O$_{13L}$										NC	I/O$_{3L}$	V$_{SS}$	I/O$_{4L}$	L
V$_{DDQL}$	NC	I/O$_{15R}$	V$_{SS}$										V$_{SS}$	NC	I/O$_{2R}$	V$_{DDQR}$	M
NC	V$_{SS}$	NC	I/O$_{15L}$										I/O$_{1R}$	V$_{DDQL}$	NC	I/O$_{2L}$	N
I/O$_{16R}$	I/O$_{16L}$	V$_{DDQR}$	NC	$\overline{\text{TRST}}$	A$_{16R}$	A$_{12R}$	A$_{8R}$	NC	V$_{DD}$	CLK$_R$	$\overline{\text{CNTEN}}_R$	A$_{4R}$	NC	I/O$_{1L}$	V$_{SS}$	NC	P
V$_{SS}$	NC	I/O$_{17R}$	TCK	A$_{17R}$(1)	A$_{13R}$	A$_{9R}$	NC	$\overline{\text{CE}}_{0R}$	V$_{SS}$	$\overline{\text{ADS}}_R$	A$_{5R}$	A$_{1R}$	V$_{SS}$	V$_{DDQL}$	I/O$_{0R}$	V$_{DDQR}$	R
NC	I/O$_{17L}$	V$_{DDQL}$	TMS	NC	A$_{14R}$	A$_{10R}$	$\overline{\text{UB}}_R$	CE$_{1R}$	V$_{SS}$	R/$\overline{\text{W}}_R$	A$_{6R}$	A$_{2R}$	V$_{SS}$	NC	V$_{SS}$	NC	T
V$_{SS}$	NC	PIPE/$\overline{\text{FT}}_R$	NC	A$_{15R}$	A$_{11R}$	A$_{7R}$	$\overline{\text{LB}}_R$	V$_{DD}$	$\overline{\text{OE}}_R$	$\overline{\text{REPEAT}}_R$	A$_{3R}$	A$_{0R}$	V$_{DD}$	OPT$_R$	NC	I/O$_{0L}$	U

70V3319/99
BF208(6)
BFG208(6)

208-Pin
fpBGA
Top View(7)

5623 drw 02c

NOTES:

1. A$_{17}$ is a NC for IDT70V3399.
2. All V$_{DD}$ pins must be connected to 3.3V power supply.
3. All V$_{DDQ}$ pins must be connected to appropriate power supply: 3.3V if OPT pin for that port is set to V$_{IH}$ (3.3V), and 2.5V if OPT pin for that port is set to V$_{IL}$ (0V).
4. All V$_{SS}$ pins must be connected to ground supply.
5. Package body is approximately 15mm x 15mm x 1.4mm with 0.8mm ball pitch.
6. This package code is used to reference the package diagram.
7. This text does not indicate orientation of the actual part-marking.

Pin Configuration(1,2,3,4,5) (con't.)

70V3319/99
BC256(6)
BCG256(6)

256-Pin BGA
Top View(7)

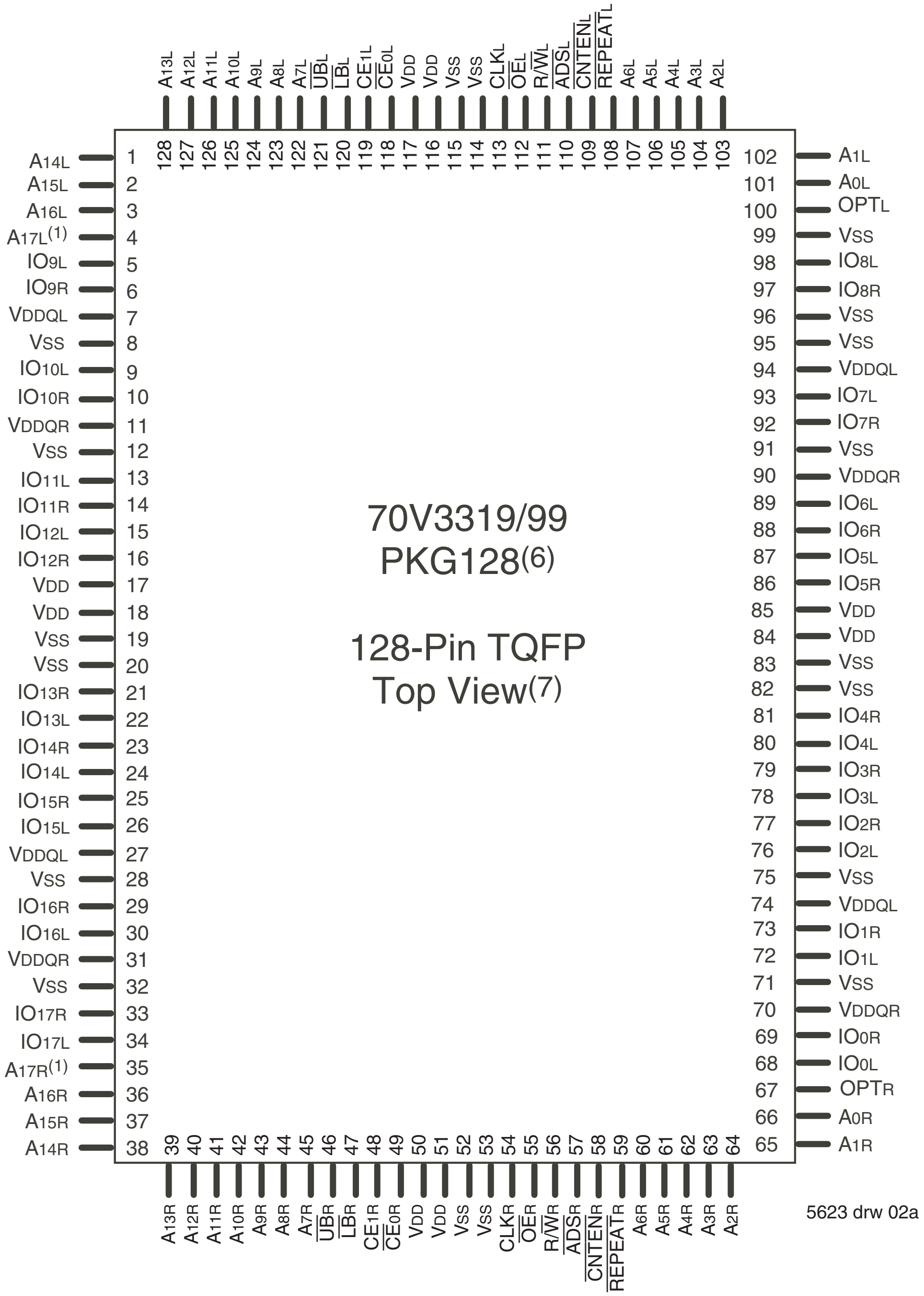
A1 NC	A2 TDI	A3 NC	A4 A_{17L}(1)	A5 A_{14L}	A6 A_{11L}	A7 A_{8L}	A8 NC	A9 CE_{1L}	A10 $\overline{OE}_L$	A11 $\overline{CNTEN}_L$	A12 A_{5L}	A13 A_{2L}	A14 A_{0L}	A15 NC	A16 NC
B1 NC	B2 NC	B3 TDO	B4 NC	B5 A_{15L}	B6 A_{12L}	B7 A_{9L}	B8 $\overline{UB}_L$	B9 $\overline{CE}_{0L}$	B10 $R/\overline{W}_L$	B11 $\overline{REPEAT}_L$	B12 A_{4L}	B13 A_{1L}	B14 V_{DD}	B15 NC	B16 NC
C1 NC	C2 I/O_{9L}	C3 V_{SS}	C4 A_{16L}	C5 A_{13L}	C6 A_{10L}	C7 A_{7L}	C8 NC	C9 $\overline{LB}_L$	C10 CLK_L	C11 $\overline{ADS}_L$	C12 A_{6L}	C13 A_{3L}	C14 OPT_L	C15 NC	C16 I/O_{8L}
D1 NC	D2 I/O_{9R}	D3 NC	D4 $PIPE/\overline{FT}_L$	D5 V_{DDQL}	D6 V_{DDQL}	D7 V_{DDQR}	D8 V_{DDQR}	D9 V_{DDQL}	D10 V_{DDQL}	D11 V_{DDQR}	D12 V_{DDQR}	D13 V_{DD}	D14 NC	D15 NC	D16 I/O_{8R}
E1 I/O_{10R}	E2 I/O_{10L}	E3 NC	E4 V_{DDQL}	E5 V_{DD}	E6 V_{DD}	E7 V_{SS}	E8 V_{SS}	E9 V_{SS}	E10 V_{SS}	E11 V_{DD}	E12 V_{DD}	E13 V_{DDQR}	E14 NC	E15 I/O_{7L}	E16 I/O_{7R}
F1 I/O_{11L}	F2 NC	F3 I/O_{11R}	F4 V_{DDQL}	F5 V_{DD}	F6 V_{SS}	F7 V_{SS}	F8 V_{SS}	F9 V_{SS}	F10 V_{SS}	F11 V_{SS}	F12 V_{DD}	F13 V_{DDQR}	F14 I/O_{6R}	F15 NC	F16 I/O_{6L}
G1 NC	G2 NC	G3 I/O_{12L}	G4 V_{DDQR}	G5 V_{SS}	G6 V_{SS}	G7 V_{SS}	G8 V_{SS}	G9 V_{SS}	G10 V_{SS}	G11 V_{SS}	G12 V_{SS}	G13 V_{DDQL}	G14 I/O_{5L}	G15 NC	G16 NC
H1 NC	H2 I/O_{12R}	H3 NC	H4 V_{DDQR}	H5 V_{SS}	H6 V_{SS}	H7 V_{SS}	H8 V_{SS}	H9 V_{SS}	H10 V_{SS}	H11 V_{SS}	H12 V_{SS}	H13 V_{DDQL}	H14 NC	H15 NC	H16 I/O_{5R}
J1 I/O_{13L}	J2 I/O_{14R}	J3 I/O_{13R}	J4 V_{DDQL}	J5 V_{SS}	J6 V_{SS}	J7 V_{SS}	J8 V_{SS}	J9 V_{SS}	J10 V_{SS}	J11 V_{SS}	J12 V_{SS}	J13 V_{DDQR}	J14 I/O_{4R}	J15 I/O_{3R}	J16 I/O_{4L}
K1 NC	K2 NC	K3 I/O_{14L}	K4 V_{DDQL}	K5 V_{SS}	K6 V_{SS}	K7 V_{SS}	K8 V_{SS}	K9 V_{SS}	K10 V_{SS}	K11 V_{SS}	K12 V_{SS}	K13 V_{DDQR}	K14 NC	K15 NC	K16 I/O_{3L}
L1 I/O_{15L}	L2 NC	L3 I/O_{15R}	L4 V_{DDQR}	L5 V_{DD}	L6 V_{SS}	L7 V_{SS}	L8 V_{SS}	L9 V_{SS}	L10 V_{SS}	L11 V_{SS}	L12 V_{DD}	L13 V_{DDQL}	L14 I/O_{2L}	L15 NC	L16 I/O_{2R}
M1 I/O_{16R}	M2 I/O_{16L}	M3 NC	M4 V_{DDQR}	M5 V_{DD}	M6 V_{DD}	M7 V_{SS}	M8 V_{SS}	M9 V_{SS}	M10 V_{SS}	M11 V_{DD}	M12 V_{DD}	M13 V_{DDQL}	M14 I/O_{1R}	M15 I/O_{1L}	M16 NC
N1 NC	N2 I/O_{17R}	N3 NC	N4 $PIPE/\overline{FT}_R$	N5 V_{DDQR}	N6 V_{DDQR}	N7 V_{DDQL}	N8 V_{DDQL}	N9 V_{DDQR}	N10 V_{DDQR}	N11 V_{DDQL}	N12 V_{DDQL}	N13 V_{DD}	N14 NC	N15 I/O_{0R}	N16 NC
P1 NC	P2 I/O_{17L}	P3 TMS	P4 A_{16R}	P5 A_{13R}	P6 A_{10R}	P7 A_{7R}	P8 NC	P9 $\overline{LB}_R$	P10 CLK_R	P11 $\overline{ADS}_R$	P12 A_{6R}	P13 A_{3R}	P14 NC	P15 NC	P16 I/O_{0L}
R1 NC	R2 NC	R3 $\overline{TRST}$	R4 NC	R5 A_{15R}	R6 A_{12R}	R7 A_{9R}	R8 $\overline{UB}_R$	R9 $\overline{CE}_{0R}$	R10 $R/\overline{W}_R$	R11 $\overline{REPEAT}_R$	R12 A_{4R}	R13 A_{1R}	R14 OPT_R	R15 NC	R16 NC
T1 NC	T2 TCK	T3 NC	T4 A_{17R}(1)	T5 A_{14R}	T6 A_{11R}	T7 A_{8R}	T8 NC	T9 CE_{1R}	T10 $\overline{OE}_R$	T11 $\overline{CNTEN}_R$	T12 A_{5R}	T13 A_{2R}	T14 A_{0R}	T15 NC	T16 NC

5623 drw 02d

NOTES:

1. A_{17} is a NC for IDT70V3399.
2. All V_{DD} pins must be connected to 3.3V power supply.
3. All V_{DDQ} pins must be connected to appropriate power supply: 3.3V if OPT pin for that port is set to V_{IH} (3.3V), and 2.5V if OPT pin for that port is set to V_{IL} (0V).
4. All V_{SS} pins must be connected to ground supply.
5. Package body is approximately 17mm x 17mm x 1.4mm, with 1.0mm ball-pitch.
6. This package code is used to reference the package diagram.
7. This text does not indicate orientation of the actual part-marking.

Pin Configuration[1,2,3,4,5,8,9] (con't.)



NOTES:
1. A_{17} is a NC for IDT70V3399.
2. All V_{DD} pins must be connected to 3.3V power supply.
3. All V_{DDQ} pins must be connected to appropriate power supply: 3.3V if OPT pin for that port is set to V_{IH} (3.3V), and 2.5V if OPT pin for that port is set to V_{IL} (0V).
4. All V_{SS} pins must be connected to ground supply.
5. Package body is approximately 14mm x 20mm x 1.4mm.
6. This package code is used to reference the package diagram.
7. This text does not indicate orientation of the actual part-marking.
8. PIPE/$\overline{FT}$ option in PKG128 is not supported due to limitation in pin count. Device is pipelined outputs only on each port.
9. Due to the limited pin count, JTAG is not supported in the PKG128 package.

Pin Names

Left Port	Right Port	Names
$\overline{\text{CE}}_{0L}$, CE$_{1L}$	$\overline{\text{CE}}_{0R}$, CE$_{1R}$	Chip Enables[6]
R/$\overline{\text{W}}_{L}$	R/$\overline{\text{W}}_{R}$	Read/Write Enable
$\overline{\text{OE}}_{L}$	$\overline{\text{OE}}_{R}$	Output Enable
A$_{0L}$ - A$_{17L}$[1]	A$_{0R}$ - A$_{17R}$[1]	Address
I/O$_{0L}$ - I/O$_{17L}$	I/O$_{0R}$ - I/O$_{17R}$	Data Input/Output
CLK$_{L}$	CLK$_{R}$	Clock
PIPE/$\overline{\text{FT}}_{L}$[5]	PIPE/$\overline{\text{FT}}_{R}$[5]	Pipeline/Flow-Through
$\overline{\text{ADS}}_{L}$	$\overline{\text{ADS}}_{R}$	Address Strobe Enable
$\overline{\text{CNTEN}}_{L}$	$\overline{\text{CNTEN}}_{R}$	Counter Enable
$\overline{\text{REPEAT}}_{L}$	$\overline{\text{REPEAT}}_{R}$	Counter Repeat[4]
$\overline{\text{UB}}_{L}$	$\overline{\text{UB}}_{R}$	Upper Byte Enable (I/O$_{9}$-I/O$_{17}$)[6]
$\overline{\text{LB}}_{L}$	$\overline{\text{LB}}_{R}$	Lower Byte Enable (I/O$_{0}$-I/O$_{8}$)[6]
V$_{DDQL}$	V$_{DDQR}$	Power (I/O Bus) (3.3V or 2.5V)[2]
OPT$_{L}$	OPT$_{R}$	Option for selecting V$_{DDQX}$[2,3]
V$_{DD}$		Power (3.3V)[2]
V$_{SS}$		Ground (0V)
TDI		Test Data Input
TDO		Test Data Output
TCK		Test Logic Clock (10MHz)
TMS		Test Mode Select
$\overline{\text{TRST}}$		Reset (Initialize TAP Controller)

5623 tbl 01

NOTES:

1. A$_{17}$ is a NC for IDT70V3399.
2. V$_{DD}$, OPT$_{X}$, and V$_{DDQX}$ must be set to appropriate operating levels prior to applying inputs on the I/Os and controls for that port.
3. OPT$_{X}$ selects the operating voltage levels for the I/Os and controls on that port. If OPT$_{X}$ is set to VIH (3.3V), then that port's I/Os and controls will operate at 3.3V levels and V$_{DDQX}$ must be supplied at 3.3V. If OPT$_{X}$ is set to VIL (0V), then that port's I/Os and address controls will operate at 2.5V levels and V$_{DDQX}$ must be supplied at 2.5V. The OPT pins are independent of one another—both ports can operate at 3.3V levels, both can operate at 2.5V levels, or either can operate at 3.3V with the other at 2.5V.
4. When $\overline{\text{REPEAT}}_{X}$ is asserted, the counter will reset to the last valid address loaded via $\overline{\text{ADS}}_{X}$.
5. PIPE/$\overline{\text{FT}}$ option in PK-128 package is not supported due to limitation in pin count. Device is pipelined output mode only on each port.
6. Chip Enables and Byte Enables are double buffered when PL/$\overline{\text{FT}}$ = V$_{IH}$, i.e., the signals take two cycles to deselect.

Truth Table I—Read/Write and Enable Control(1,2,3)

$\overline{\text{OE}}$	CLK	$\overline{\text{CE}}_0$	CE$_1$	$\overline{\text{UB}}$	$\overline{\text{LB}}$	R/$\overline{\text{W}}$	Upper Byte I/O$_{9-17}$	Lower Byte I/O$_{0-8}$	MODE
X	↑	H	X	X	X	X	High-Z	High-Z	Deselected–Power Down
X	↑	X	L	X	X	X	High-Z	High-Z	Deselected–Power Down
X	↑	L	H	H	H	X	High-Z	High-Z	Both Bytes Deselected
X	↑	L	H	H	L	L	High-Z	D$_{IN}$	Write to Lower Byte Only
X	↑	L	H	L	H	L	D$_{IN}$	High-Z	Write to Upper Byte Only
X	↑	L	H	L	L	L	D$_{IN}$	D$_{IN}$	Write to Both Bytes
L	↑	L	H	H	L	H	High-Z	D$_{OUT}$	Read Lower Byte Only
L	↑	L	H	L	H	H	D$_{OUT}$	High-Z	Read Upper Byte Only
L	↑	L	H	L	L	H	D$_{OUT}$	D$_{OUT}$	Read Both Bytes
H	↑	L	H	L	L	X	High-Z	High-Z	Outputs Disabled

5623 tbl 02

NOTES:
1. "H" = V$_{IH}$, "L" = V$_{IL}$, "X" = Don't Care.
2. $\overline{\text{ADS}}$, $\overline{\text{CNTEN}}$, $\overline{\text{REPEAT}}$ = X.
3. $\overline{\text{OE}}$ is an asynchronous input signal.

Truth Table II—Address Counter Control(1,2)

External Address	Previous Internal Address	Internal Address Used	CLK	$\overline{\text{ADS}}$	$\overline{\text{CNTEN}}$	$\overline{\text{REPEAT}}$(6)	I/O(3)	MODE
X	X	An	↑	X	X	L(4)	D$_{I/O}$(0)	Counter Reset to last valid $\overline{\text{ADS}}$ load
An	X	An	↑	L(4)	X	H	D$_{I/O}$ (n)	External Address Used
An	Ap	Ap	↑	H	H	H	D$_{I/O}$(p)	External Address Blocked—Counter disabled (Ap reused)
X	Ap	Ap + 1	↑	H	L(5)	H	D$_{I/O}$(p+1)	Counter Enabled—Internal Address generation

5623 tbl 03

NOTES:
1. "H" = V$_{IH}$, "L" = V$_{IL}$, "X" = Don't Care.
2. Read and write operations are controlled by the appropriate setting of R/$\overline{\text{W}}$, $\overline{\text{CE}}_0$, CE$_1$, $\overline{\text{UB}}$, $\overline{\text{LB}}$ and $\overline{\text{OE}}$.
3. Outputs configured in flow-through output mode: if outputs are in pipelined mode the date out will be delayed by one cycle.
4. $\overline{\text{ADS}}$ and $\overline{\text{REPEAT}}$ are independent of all other memory control signals including $\overline{\text{CE}}_0$, CE$_1$ and $\overline{\text{UB}}$, $\overline{\text{LB}}$.
5. The address counter advances if $\overline{\text{CNTEN}}$ = V$_{IL}$ on the rising edge of CLK, regardless of all other memory control signals including $\overline{\text{CE}}_0$, CE$_1$, $\overline{\text{UB}}$, $\overline{\text{LB}}$.
6. When $\overline{\text{REPEAT}}$ is asserted, the counter will reset to the last valid address loaded via $\overline{\text{ADS}}$. This value is not set at power-up: a known location should be loaded via $\overline{\text{ADS}}$ during initialization if desired. Any subsequent $\overline{\text{ADS}}$ access during operations will update the $\overline{\text{REPEAT}}$ address location.

Recommended Operating Temperature and Supply Voltage(1)

Grade	Ambient Temperature	GND	V_{DD}
Commercial	0°C to +70°C	0V	3.3V ± 150mV
Industrial	-40°C to +85°C	0V	3.3V ± 150mV

5623 tbl 04

NOTES:

1. This is the parameter TA. This is the "instant on" case temperature.

Absolute Maximum Ratings(1)

Symbol	Rating	Commercial & Industrial	Unit
V_{TERM}(2)	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
T_{BIAS}(3)	Temperature Under Bias	-55 to +125	°C
T_{STG}	Storage Temperature	-65 to +150	°C
T_{JN}	Junction Temperature	+150	°C
I_{OUT}	DC Output Current	50	mA

5623 tbl 06

NOTES:

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. V_{TERM} must not exceed V_{DD} + 150mV for more than 25% of the cycle time or 4ns maximum, and is limited to ≤ 20mA for the period of V_{TERM} ≥ V_{DD} + 150mV.
3. Ambient Temperature Under Bias. No AC Conditions. Chip Deselected.

Recommended DC Operating Conditions with V_{DDQ} at 2.5V

Symbol	Parameter	Min.	Typ.	Max.	Unit
V_{DD}	Core Supply Voltage	3.15	3.3	3.45	V
V_{DDQ}	I/O Supply Voltage(3)	2.4	2.5	2.6	V
V_{SS}	Ground	0	0	0	V
V_{IH}	Input High Voltage (Address & Control Inputs)	1.7	—	V_{DDQ} + 100mV(2)	V
V_{IH}	Input High Voltage - I/O(3)	1.7	—	V_{DDQ} + 100mV(2)	V
V_{IL}	Input Low Voltage	-0.3(1)	—	0.7	V

5623 tbl 05a

NOTES:

1. Undershoot of V_{IL} ≥ -1.5V for pulse width less than 10ns is allowed.
2. V_{TERM} must not exceed V_{DDQ} + 100mV.
3. To select operation at 2.5V levels on the I/Os and controls of a given port, the OPT pin for that port must be set to V_{IL} (0V), and V_{DDQX} for that port must be supplied as indicated above.

Recommended DC Operating Conditions with V_{DDQ} at 3.3V

Symbol	Parameter	Min.	Typ.	Max.	Unit
V_{DD}	Core Supply Voltage	3.15	3.3	3.45	V
V_{DDQ}	I/O Supply Voltage(3)	3.15	3.3	3.45	V
V_{SS}	Ground	0	0	0	V
V_{IH}	Input High Voltage (Address & Control Inputs)(3)	2.0	—	V_{DDQ} + 150mV(2)	V
V_{IH}	Input High Voltage - I/O(3)	2.0	—	V_{DDQ} + 150mV(2)	V
V_{IL}	Input Low Voltage	-0.3(1)	—	0.8	V

5623 tbl 05b

NOTES:

1. Undershoot of V_{IL} ≥ -1.5V for pulse width less than 10ns is allowed.
2. V_{TERM} must not exceed V_{DDQ} + 150mV.
3. To select operation at 3.3V levels on the I/Os and controls of a given port, the OPT pin for that port must be set to V_{IH} (3.3V), and V_{DDQX} for that port must be supplied as indicated above.

Capacitance(1) (T_A = +25°C, F = 1.0MHz)

Symbol	Parameter	Conditions(2)	Max.	Unit
C_{IN}	Input Capacitance	V_{IN} = 3dV	8	pF
C_{OUT}(3)	Output Capacitance	V_{OUT} = 3dV	10.5	pF

5623 tbl 07

NOTES:

1. These parameters are determined by device characterization, but are not production tested.
2. 3dV references the interpolated capacitance when the input and output switch from 0V to 3V or from 3V to 0V.
3. C_{OUT} also references $C_{I/O}$.

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range (V_{DD} = 3.3V ± 150mV)

Symbol	Parameter	Test Conditions	70V3319/99S		Unit
			Min.	Max.	
$\lvert I_{LI} \rvert$	Input Leakage Current(1)	V_{DDQ} = Max., V_{IN} = 0V to V_{DDQ}	—	10	µA
$\lvert I_{LO} \rvert$	Output Leakage Currentt(1)	$\overline{CE}_0$ = V_{IH} or CE_1 = V_{IL}, V_{OUT} = 0V to V_{DDQ}	—	10	µA
V_{OL} (3.3V)	Output Low Voltage(2)	I_{OL} = +4mA, V_{DDQ} = Min.	—	0.4	V
V_{OH} (3.3V)	Output High Voltage(2)	I_{OH} = -4mA, V_{DDQ} = Min.	2.4	—	V
V_{OL} (2.5V)	Output Low Voltage(2)	I_{OL} = +2mA, V_{DDQ} = Min.	—	0.4	V
V_{OH} (2.5V)	Output High Voltage(2)	I_{OH} = -2mA, V_{DDQ} = Min.	2.0	—	V

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NOTE:

1. At $V_{DD} \leq 2.0$V leakages are undefined.
2. V_{DDQ} is selectable (3.3V/2.5V) via OPT pins. Refer to p.5 for details.

DC Electrical Characteristics Over the Operating Temperature and Supply Voltage Range(3) (V_{DD} = 3.3V ± 150mV)

Symbol	Parameter	Test Condition	Version		70V3319/99S166 Com'l Only		70V3319/99S133 Com'l & Ind		Unit
					Typ.[4]	Max.	Typ.[4]	Max.	
I_{DD}	Dynamic Operating Current (Both Ports Active)	$\overline{CE}_L$ and $\overline{CE}_R = V_{IL}$, Outputs Disabled, $f = f_{MAX}$[1]	COM'L	S	370	500	320	400	mA
			IND	S	—	—	320	480	
I_{SB1}	Standby Current (Both Ports - TTL Level Inputs)	$\overline{CE}_L = \overline{CE}_R = V_{IH}$, Outputs Disabled, $f = f_{MAX}$[1]	COM'L	S	125	200	115	160	mA
			IND	S	—	—	115	195	
I_{SB2}	Standby Current (One Port - TTL Level Inputs)	$\overline{CE}_{"A"} = V_{IL}$ and $\overline{CE}_{"B"} = V_{IH}$[5] Active Port Outputs Disabled, $f=f_{MAX}$[1]	COM'L	S	250	350	220	290	mA
			IND	S	—	—	220	350	
I_{SB3}	Full Standby Current (Both Ports - CMOS Level Inputs)	Both Ports Outputs Disabled $\overline{CE}_L$ and $\overline{CE}_R \geq V_{DDQ} - 0.2V$, $V_{IN} \geq V_{DDQ} - 0.2V$ or $V_{IN} \leq 0.2V$, $f = 0$[2]	COM'L	S	15	30	15	30	mA
			IND	S	—	—	15	40	
I_{SB4}	Full Standby Current (One Port - CMOS Level Inputs)	$\overline{CE}_{"A"} \leq 0.2V$ and $\overline{CE}_{"B"} \geq V_{DDQ} - 0.2V$[5] $V_{IN} \geq V_{DDQ} - 0.2V$ or $V_{IN} \leq 0.2V$ Active Port, Outputs Disabled, $f = f_{MAX}$[1]	COM'L	S	250	350	220	290	mA
			IND	S	—	—	220	350	

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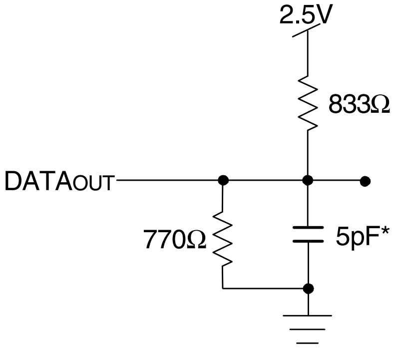
NOTES:

1. At $f = f_{MAX}$, address and control lines (except Output Enable) are cycling at the maximum frequency clock cycle of $1/t_{CYC}$, using "AC TEST CONDITIONS" at input levels of GND to 3V.
2. f = 0 means no address, clock, or control lines change. Applies only to input at CMOS level standby.
3. Port "A" may be either left or right port. Port "B" is the opposite from port "A".
4. V_{DD} = 3.3V, T_A = 25°C for Typ, and are not production tested. **I_{DD} DC**(f=0) = 120mA (Typ).
5. $\overline{CE}_X = V_{IL}$ means $\overline{CE}_{0X} = V_{IL}$ and $CE_{1X} = V_{IH}$
   $\overline{CE}_X = V_{IH}$ means $\overline{CE}_{0X} = V_{IH}$ or $CE_{1X} = V_{IL}$
   $\overline{CE}_X \leq 0.2V$ means $\overline{CE}_{0X} \leq 0.2V$ and $CE_{1X} \geq V_{DDQ} - 0.2V$
   $\overline{CE}_X \geq V_{DDQ} - 0.2V$ means $\overline{CE}_{0X} \geq V_{DDQ} - 0.2V$ or $CE_{1X} - 0.2V$
   "X" represents "L" for left port or "R" for right port.

AC Test Conditions (VDDQ - 3.3V/2.5V)

Input Pulse Levels (Address & Controls)	GND to 3.0V/GND to 2.4V
Input Pulse Levels (I/Os)	GND to 3.0V/GND to 2.4V
Input Rise/Fall Times	2ns
Input Timing Reference Levels	1.5V/1.25V
Output Reference Levels	1.5V/1.25V
Output Load	Figures 1 and 2

5623 tbl 10



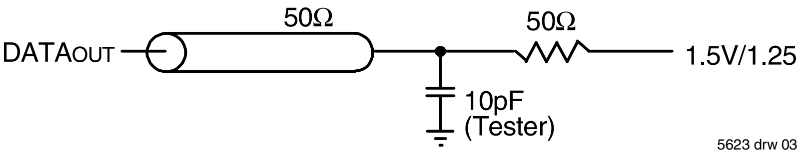


Figure 1. AC Output Test load.

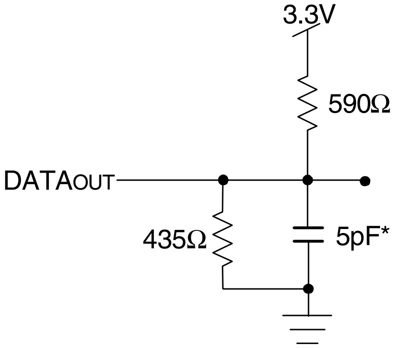


Figure 2. Output Test Load
(For tCKLZ, tCKHZ, tOLZ, and tOHZ).
*Including scope and jig.

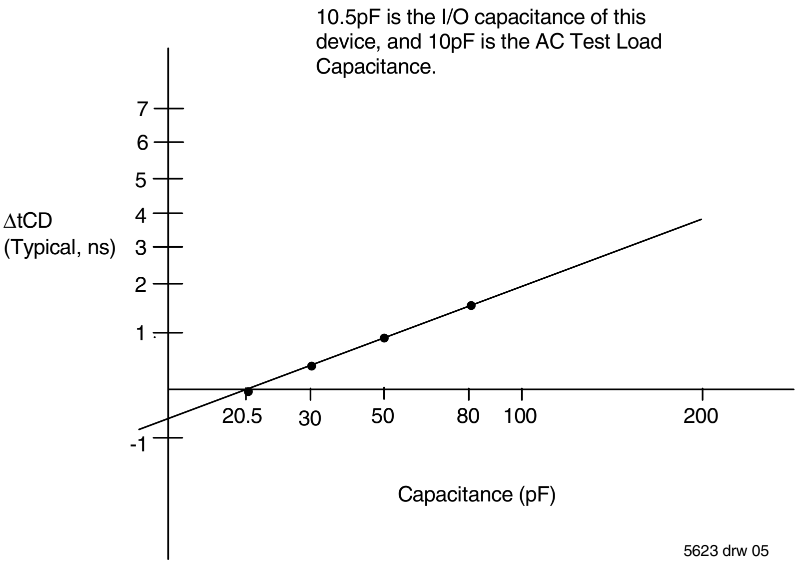


Figure 3. Typical Output Derating (Lumped Capacitive Load).

AC Electrical Characteristics Over the Operating Temperature Range (Read and Write Cycle Timing)[2,3] (V_{DD} = 3.3V ± 150mV, T_A = 0°C to +70°C)

		70V3319/99S166 Com'l Only		70V3319/99S133 Com'l & Ind		
Symbol	**Parameter**	**Min.**	**Max.**	**Min.**	**Max.**	**Unit**
t_{CYC1}	Clock Cycle Time (Flow-Through)[1]	20	—	25	—	ns
t_{CYC2}	Clock Cycle Time (Pipelined)[1]	6	—	7.5	—	ns
t_{CH1}	Clock High Time (Flow-Through)[1]	6	—	7	—	ns
t_{CL1}	Clock Low Time (Flow-Through)[1]	6	—	7	—	ns
t_{CH2}	Clock High Time (Pipelined)[2]	2.1	—	2.6	—	ns
t_{CL2}	Clock Low Time (Pipelined)[1]	2.1	—	2.6	—	ns
t_{SA}	Address Setup Time	1.7	—	1.8	—	ns
t_{HA}	Address Hold Time	0.5	—	0.5	—	ns
t_{SC}	Chip Enable Setup Time	1.7	—	1.8	—	ns
t_{HC}	Chip Enable Hold Time	0.5	—	0.5	—	ns
t_{SB}	Byte Enable Setup Time	1.7	—	1.8	—	ns
t_{HB}	Byte Enable Hold Time	0.5	—	0.5	—	ns
t_{SW}	R/W Setup Time	1.7	—	1.8	—	ns
t_{HW}	R/W Hold Time	0.5	—	0.5	—	ns
t_{SD}	Input Data Setup Time	1.7	—	1.8	—	ns
t_{HD}	Input Data Hold Time	0.5	—	0.5	—	ns
t_{SAD}	$\overline{ADS}$ Setup Time	1.7	—	1.8	—	ns
t_{HAD}	$\overline{ADS}$ Hold Time	0.5	—	0.5	—	ns
t_{SCN}	$\overline{CNTEN}$ Setup Time	1.7	—	1.8	—	ns
t_{HCN}	$\overline{CNTEN}$ Hold Time	0.5	—	0.5	—	ns
t_{SRPT}	$\overline{REPEAT}$ Setup Time	1.7	—	1.8	—	ns
t_{HRPT}	$\overline{REPEAT}$ Hold Time	0.5	—	0.5	—	ns
t_{OE}	Output Enable to Data Valid	—	4.0	—	4.2	ns
t_{OLZ}	Output Enable to Output Low-Z	1	—	1	—	ns
t_{OHZ}	Output Enable to Output High-Z	1	3.6	1	4.2	ns
t_{CD1}	Clock to Data Valid (Flow-Through)[1]	—	12	—	15	ns
t_{CD2}	Clock to Data Valid (Pipelined)[1]	—	3.6	—	4.2	ns
t_{DC}	Data Output Hold After Clock High	1	—	1	—	ns
t_{CKHZ}	Clock High to Output High-Z	1	3	1	3	ns
t_{CKLZ}	Clock High to Output Low-Z	1	—	1	—	ns
Port-to-Port Delay						
t_{CO}	Clock-to-Clock Offset	5	—	6	—	ns

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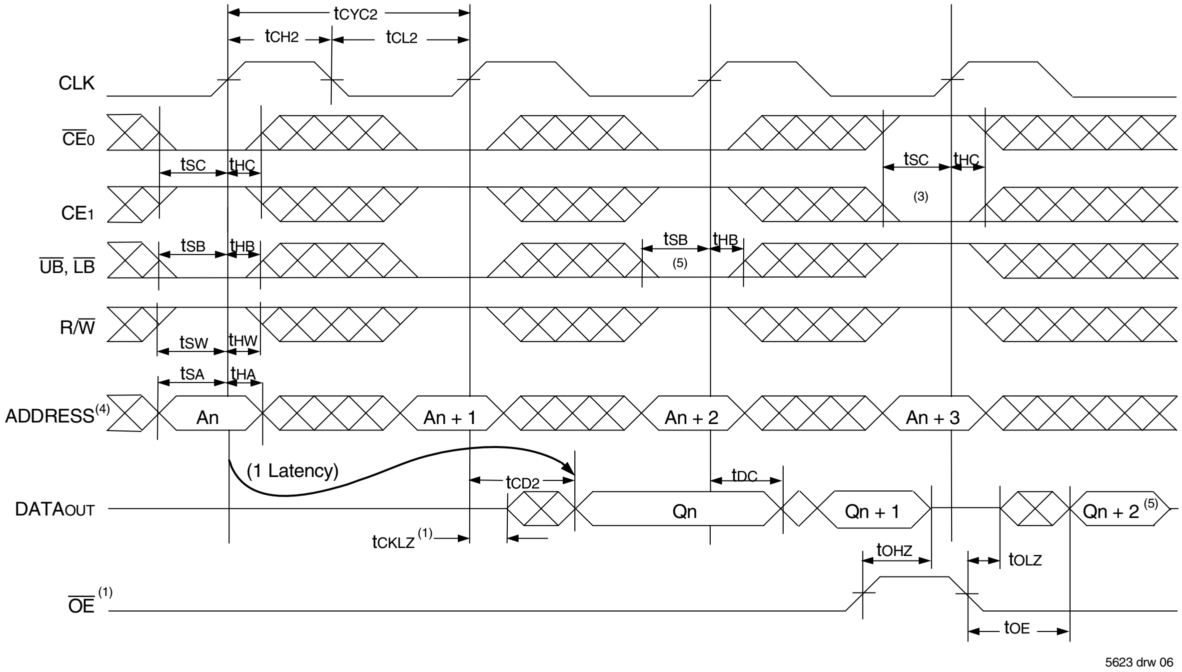
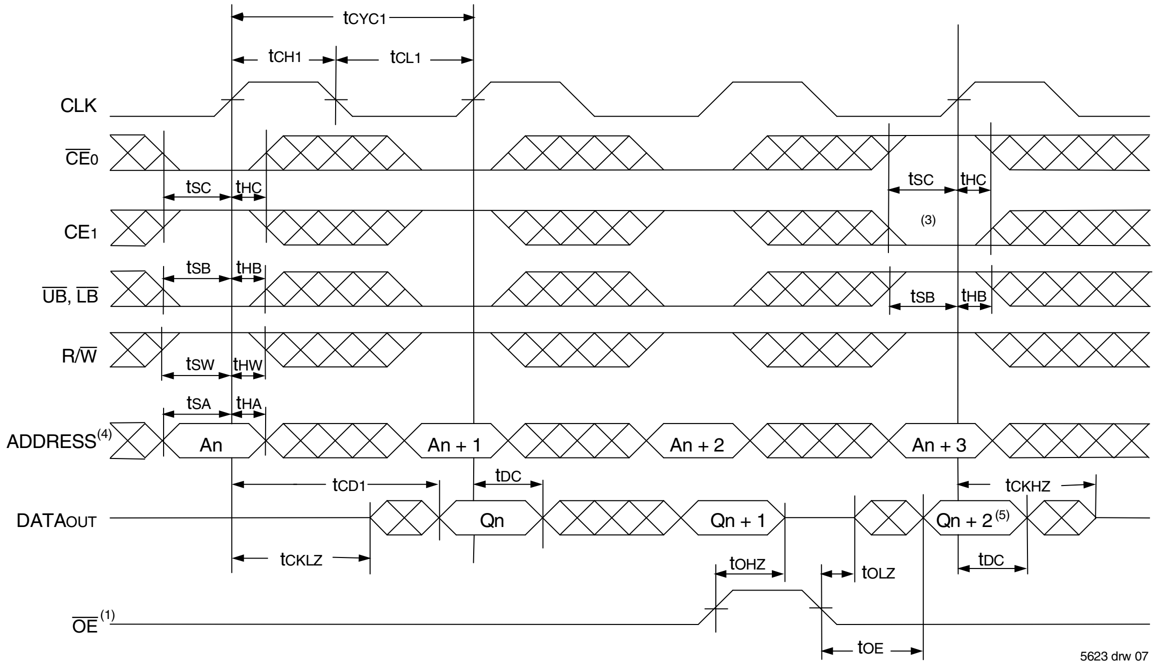
NOTES:

1. The Pipelined output parameters (t_{CYC2}, t_{CD2}) apply to either or both left and right ports when $\overline{FT}$/PIPE$_X$ = V_{IH}. Flow-through parameters (t_{CYC1}, t_{CD1}) apply when $\overline{FT}$/PIPE = V_{IL} for that port.
2. All input signals are synchronous with respect to the clock except for the asynchronous Output Enable ($\overline{OE}$) and $\overline{FT}$/PIPE. $\overline{FT}$/PIPE should be treated as a DC signal, i.e. steady state during operation.
3. These values are valid for either level of V_{DDQ} (3.3V/2.5V). See page 5 for details on selecting the desired operating voltage levels for each port.

Timing Waveform of Read Cycle for Pipelined Operation ($\overline{\text{FT}}$/PIPE'X' = V_{IH})(2)



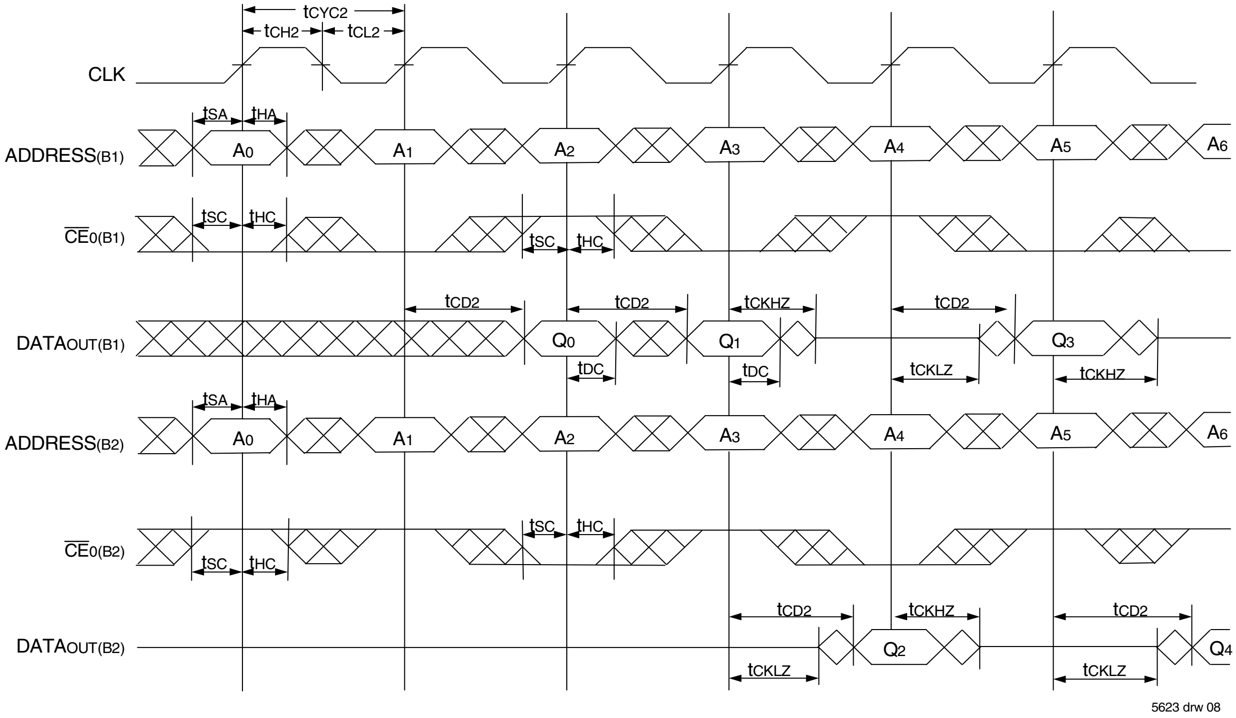
Timing Waveform of Read Cycle for Flow-through Output ($\overline{\text{FT}}$/PIPE"X" = V_{IL})(2,6)



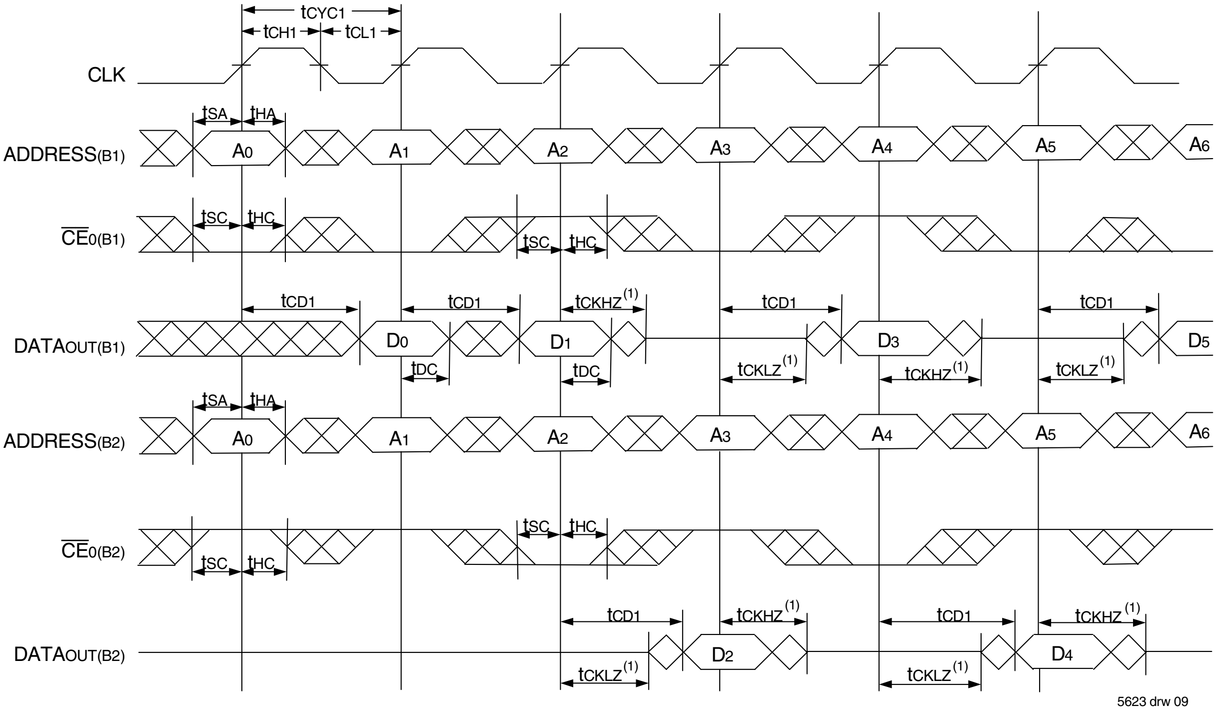
NOTES:

1. $\overline{OE}$ is asynchronously controlled; all other inputs are synchronous to the rising clock edge.
2. $\overline{ADS}$ = V_{IL}, $\overline{CNTEN}$ and $\overline{REPEAT}$ = V_{IH}.
3. The output is disabled (High-Impedance state) by $\overline{CE_0}$ = V_{IH}, CE_1 = V_{IL}, $\overline{UB}$, $\overline{LB}$ = V_{IH} following the next rising edge of the clock. Refer to Truth Table 1.
4. Addresses do not have to be accessed sequentially since $\overline{ADS}$ = V_{IL} constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
5. If $\overline{UB}$, $\overline{LB}$ was HIGH, then the appropriate Byte of DATAOUT for Qn + 2 would be disabled (High-Impedance state).
6. "x" denotes Left or Right port. The diagram is with respect to that port.

Timing Waveform of a Multi-Device Pipelined Read(1,2)



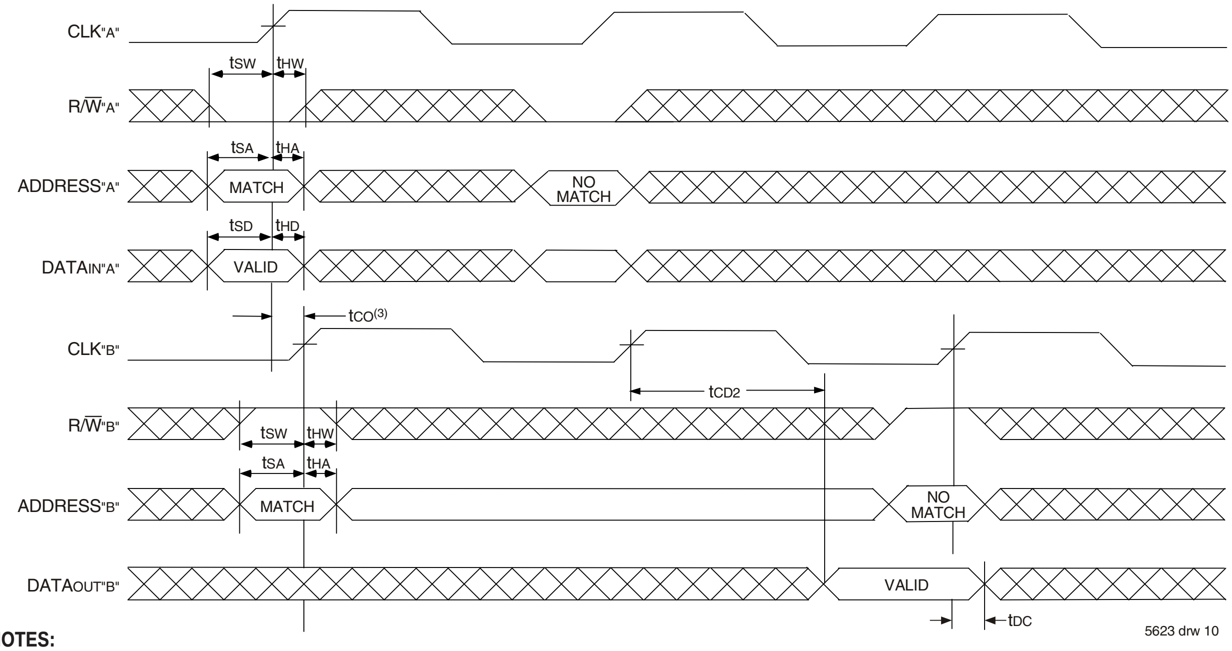
Timing Waveform of a Multi-Device Flow-Through Read(1,2)



NOTES:

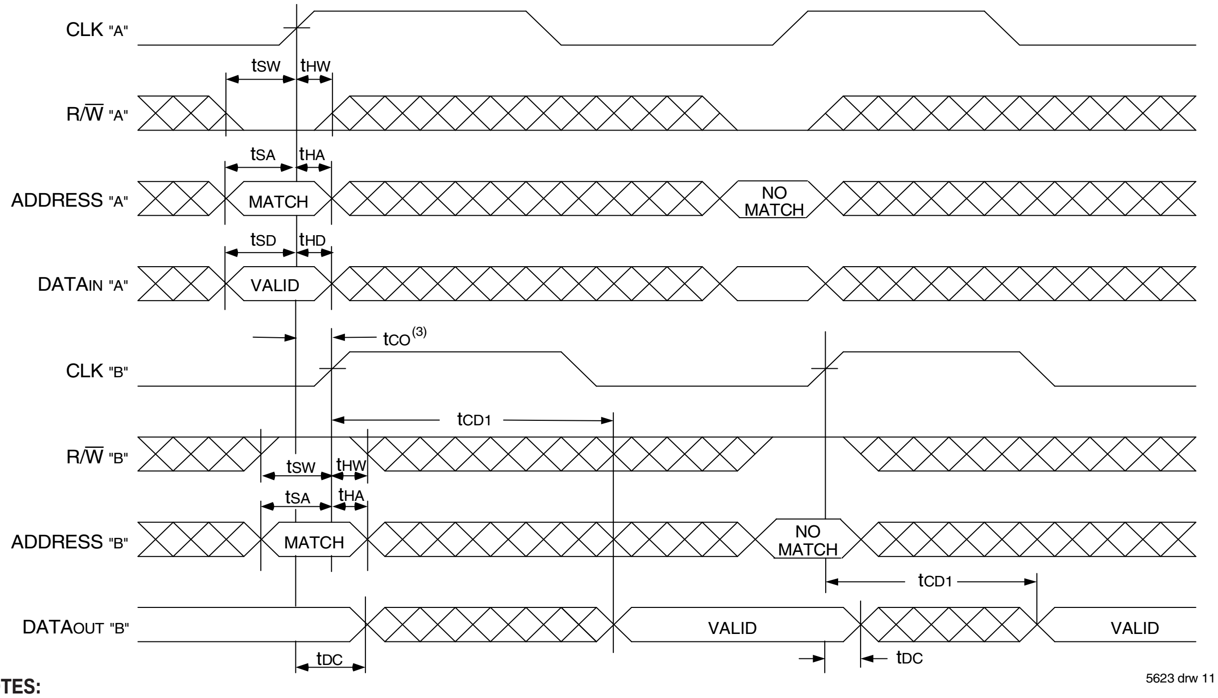
1. B1 Represents Device #1; B2 Represents Device #2. Each Device consists of one IDT70V3319/99 for this waveform, and are setup for depth expansion in this example. ADDRESS$_{(B1)}$ = ADDRESS$_{(B2)}$ in this situation.
2. $\overline{UB}$, $\overline{LB}$, $\overline{OE}$, and $\overline{ADS}$ = V_{IL}; $CE_{1(B1)}$, $CE_{1(B2)}$, R/$\overline{W}$, $\overline{CNTEN}$, and $\overline{REPEAT}$ = V_{IH}.

Timing Waveform of Left Port Write to Pipelined Right Port Read[(1,2,4)]



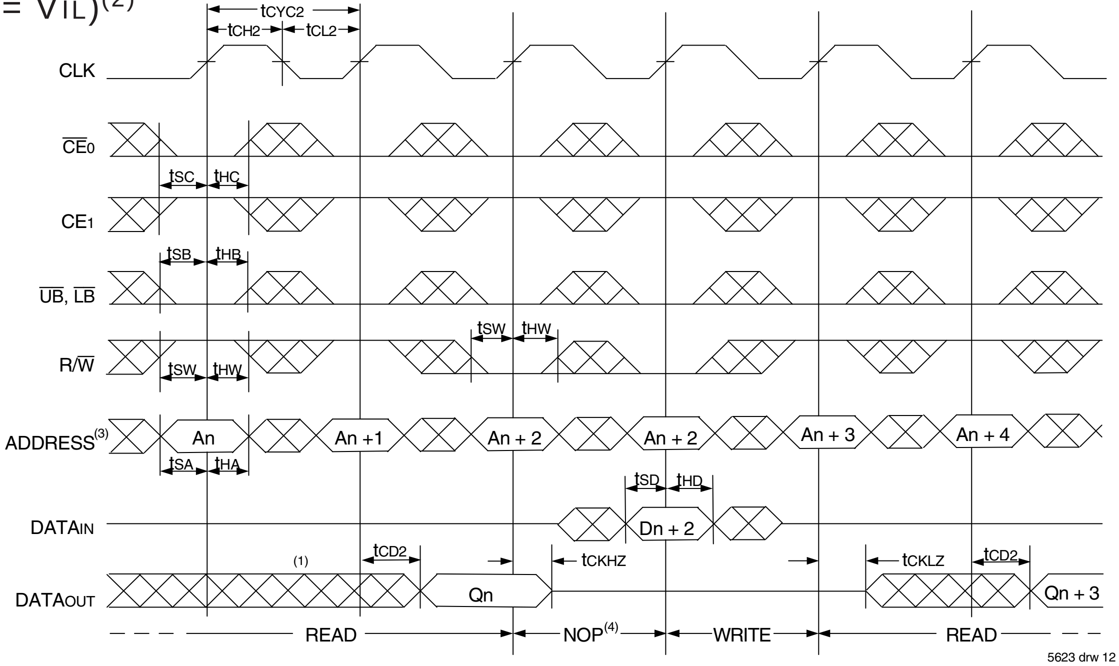
NOTES:
1. $\overline{CE}_0$, $\overline{UB}$, $\overline{LB}$, and $\overline{ADS}$ = V_{IL}; CE_1, $\overline{CNTEN}$, and $\overline{REPEAT}$ = V_{IH}.
2. $\overline{OE}$ = V_{IL} for Port "B", which is being read from. $\overline{OE}$ = V_{IH} for Port "A", which is being written to.
3. If $t_{CO} \leq$ minimum specified, then data from Port "B" read is not valid until following Port "B" clock cycle (ie, time from write to valid read on opposite port will be t_{CO} + 2 t_{CYC2} + t_{CD2}). If t_{CO} > minimum, then data from Port "B" read is available on first Port "B" clock cycle (ie, time from write to valid read on opposite port will be t_{CO} + t_{CYC2} + t_{CD2}).
4. All timing is the same for Left and Right ports. Port "A" may be either Left or Right port. Port "B" is the opposite of Port "A"

Timing Waveform with Port-to-Port Flow-Through Read[(1,2,4)]



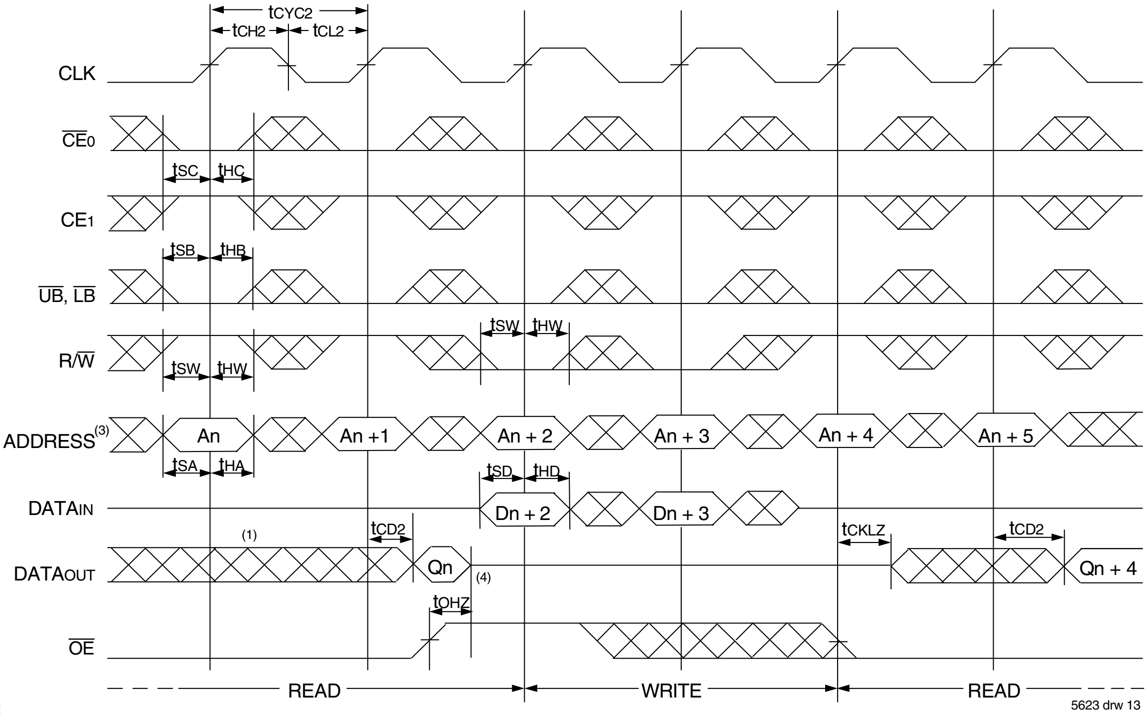
NOTES:
1. $\overline{CE}_0$, $\overline{UB}$, $\overline{LB}$, and $\overline{ADS}$ = V_{IL}; CE_1, $\overline{CNTEN}$, and $\overline{REPEAT}$ = V_{IH}.
2. $\overline{OE}$ = V_{IL} for the Right Port, which is being read from. $\overline{OE}$ = V_{IH} for the Left Port, which is being written to.
3. If $t_{CO} \leq$ minimum specified, then data from Port "B" read is not valid until following Port "B" clock cycle (i.e., time from write to valid read on opposite port will be t_{CO} + t_{CYC} + t_{CD1}). If t_{CO} > minimum, then data from Port "B" read is available on first Port "B" clock cycle (i.e., time from write to valid read on opposite port will be t_{CO} + t_{CD1}).
4. All timing is the same for both left and right ports. Port "A" may be either left or right port. Port "B" is the opposite of Port "A".

Timing Waveform of Pipelined Read-to-Write-to-Read ($\overline{OE}$ = VIL)(2)



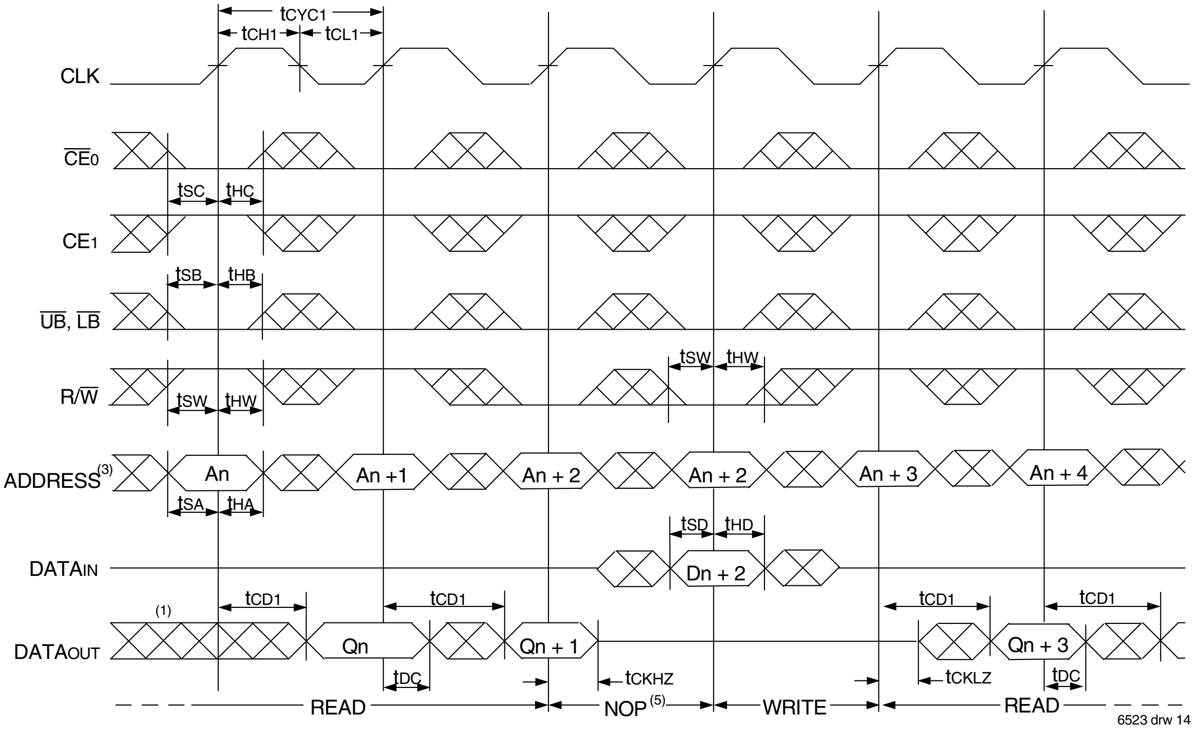
NOTES:
1. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
2. $\overline{CE}_0$, $\overline{UB}$, $\overline{LB}$, and $\overline{ADS}$ = VIL; CE1, $\overline{CNTEN}$, and $\overline{REPEAT}$ = VIH. "NOP" is "No Operation".
3. Addresses do not have to be accessed sequentially since $\overline{ADS}$ = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
4. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be rewritten to guarantee data integrity.

Timing Waveform of Pipelined Read-to-Write-to-Read ($\overline{OE}$ Controlled)(2)

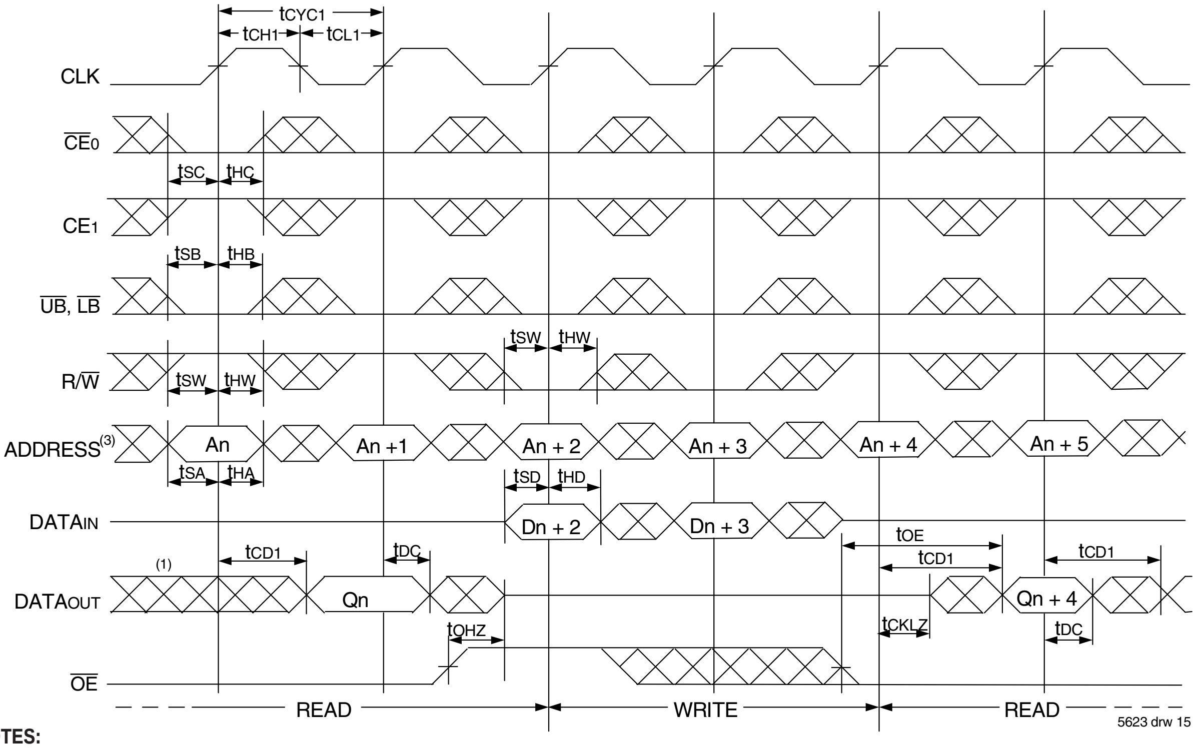


NOTES:
1. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
2. $\overline{CE}_0$, $\overline{UB}$, $\overline{LB}$, and $\overline{ADS}$ = VIL; CE1, $\overline{CNTEN}$, and $\overline{REPEAT}$ = VIH.
3. Addresses do not have to be accessed sequentially since $\overline{ADS}$ = VIL constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
4. This timing does not meet requirements for fastest speed grade. This waveform indicates how logically it could be done if timing so allows.

Timing Waveform of Flow-Through Read-to-Write-to-Read ($\overline{OE}$ = V_{IL})(2)



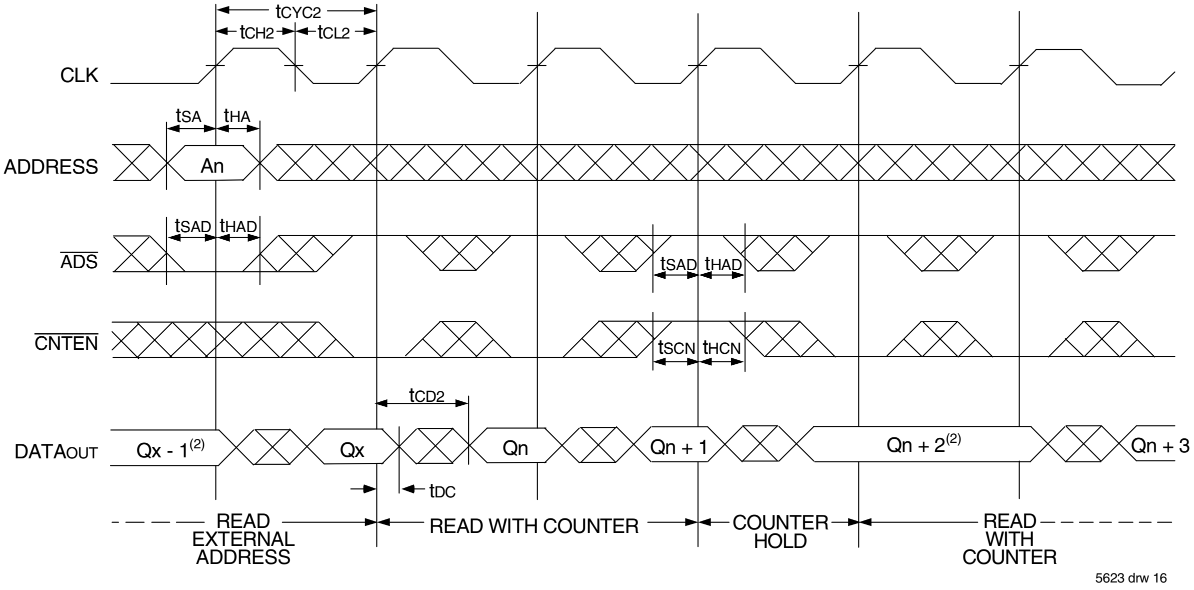
Timing Waveform of Flow-Through Read-to-Write-to-Read ($\overline{OE}$ Controlled)(2)



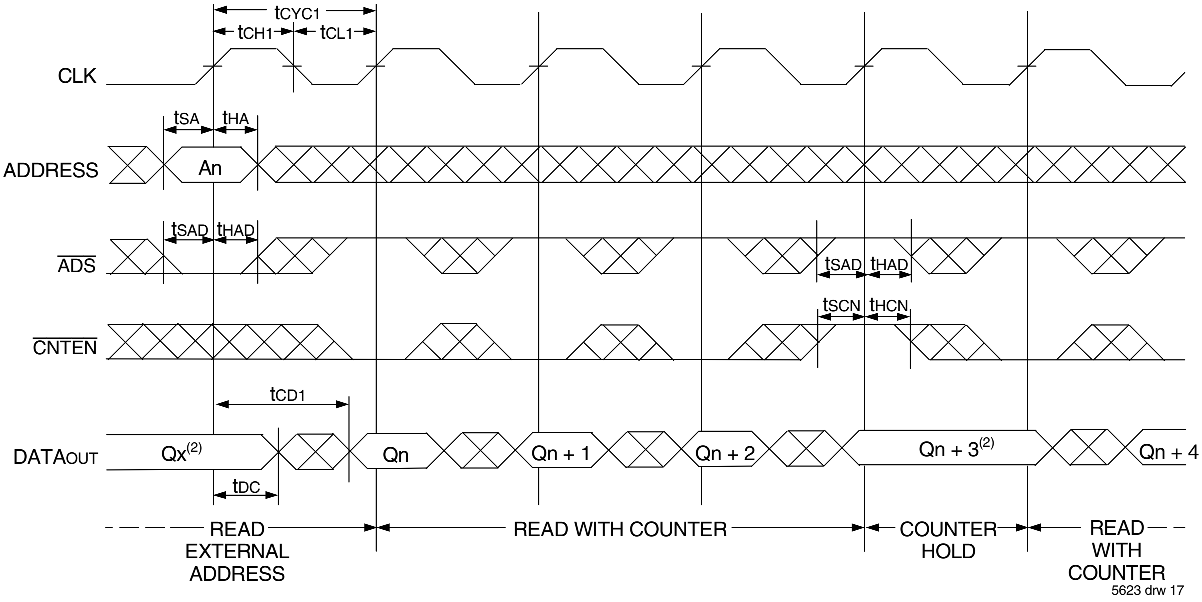
NOTES:

1. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
2. $\overline{CE}_0$, $\overline{UB}$, $\overline{LB}$, and $\overline{ADS}$ = V_{IL}; CE_1, $\overline{CNTEN}$, and $\overline{REPEAT}$ = V_{IH}.
3. Addresses do not have to be accessed sequentially since $\overline{ADS}$ = V_{IL} constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
4. "NOP" is "No Operation." Data in memory at the selected address may be corrupted and should be rewritten to guarantee data integrity.

Timing Waveform of Pipelined Read with Address Counter Advance[1]



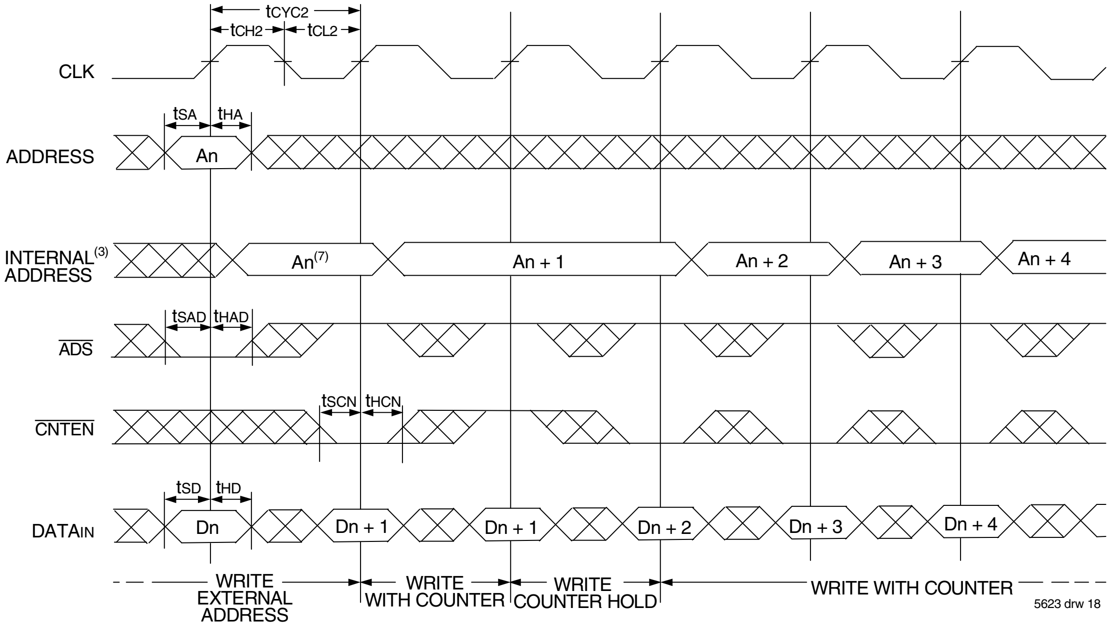
Timing Waveform of Flow-Through Read with Address Counter Advance[1]



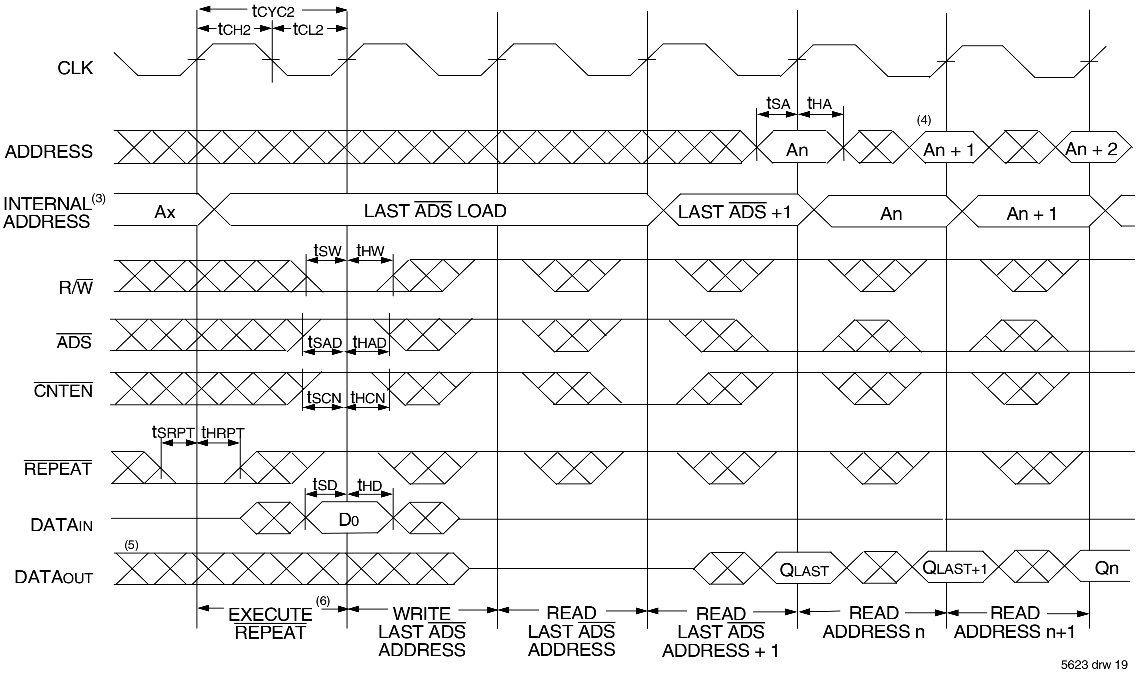
NOTES:

1. $\overline{CE_0}$, $\overline{OE}$, $\overline{UB}$, $\overline{LB}$ = V_{IL}; CE_1, $R/\overline{W}$, and $\overline{REPEAT}$ = V_{IH}.
2. If there is no address change via $\overline{ADS}$ = V_{IL} (loading a new address) or $\overline{CNTEN}$ = V_{IL} (advancing the address), i.e. $\overline{ADS}$ = V_{IH} and $\overline{CNTEN}$ = V_{IH}, then the data output remains constant for subsequent clocks.

Timing Waveform of Write with Address Counter Advance (Flow-through or Pipelined Inputs)(1)



Timing Waveform of Counter Repeat(2)



NOTES:

1. $\overline{CE_0}$, $\overline{UB}$, $\overline{LB}$, and R/$\overline{W}$ = V_{IL}; CE_1 and $\overline{REPEAT}$ = V_{IH}.
2. $\overline{CE_0}$, $\overline{UB}$, $\overline{LB}$ = V_{IL}; CE_1 = V_{IH}.
3. The "Internal Address" is equal to the "External Address" when $\overline{ADS}$ = V_{IL} and equals the counter output when $\overline{ADS}$ = V_{IH}.
4. Addresses do not have to be accessed sequentially since $\overline{ADS}$ = V_{IL} constantly loads the address on the rising edge of the CLK; numbers are for reference use only.
5. Output state (High, Low, or High-impedance) is determined by the previous cycle control signals.
6. No dead cycle exists during $\overline{REPEAT}$ operation. A READ or WRITE cycle may be coincidental with the counter $\overline{REPEAT}$ cycle: Address loaded by last valid $\overline{ADS}$ load will be accessed. Extra cycles are shown here simply for clarification. For more information on $\overline{REPEAT}$ function refer to Truth Table II.
7. $\overline{CNTEN}$ = V_{IL} advances Internal Address from 'An' to 'An +1'. The transition shown indicates the time required for the counter to advance. The 'An +1'Address is written to during this cycle.

Functional Description

The IDT70V3319/99 provides a true synchronous Dual-Port Static RAM interface. Registered inputs provide minimal set-up and hold times on address, data, and all critical control inputs. All internal registers are clocked on the rising edge of the clock signal, however, the self-timed internal write pulse is independent of the LOW to HIGH transition of the clock signal.

An asynchronous output enable is provided to ease asynchronous bus interfacing. Counter enable inputs are also provided to stall the operation of the address counters for fast interleaved memory applications.

A HIGH on $\overline{CE}_0$ or a LOW on CE_1 for one clock cycle will power down the internal circuitry to reduce static power consumption. Multiple chip enables allow easier banking of multiple IDT70V3319/99s for depth expansion configurations. Two cycles are required with $\overline{CE}_0$ LOW and CE_1 HIGH to reactivate the outputs.

Depth and Width Expansion

The IDT70V3319/99 features dual chip enables (refer to Truth Table I) in order to facilitate rapid and simple depth expansion with no requirements for external logic. Figure 4 illustrates how to control the various chip enables in order to expand two devices in depth.

The IDT70V3319/99 can also be used in applications requiring expanded width, as indicated in Figure 4. Through combining the control signals, the devices can be grouped as necessary to accommodate applications needing 36-bits or wider.

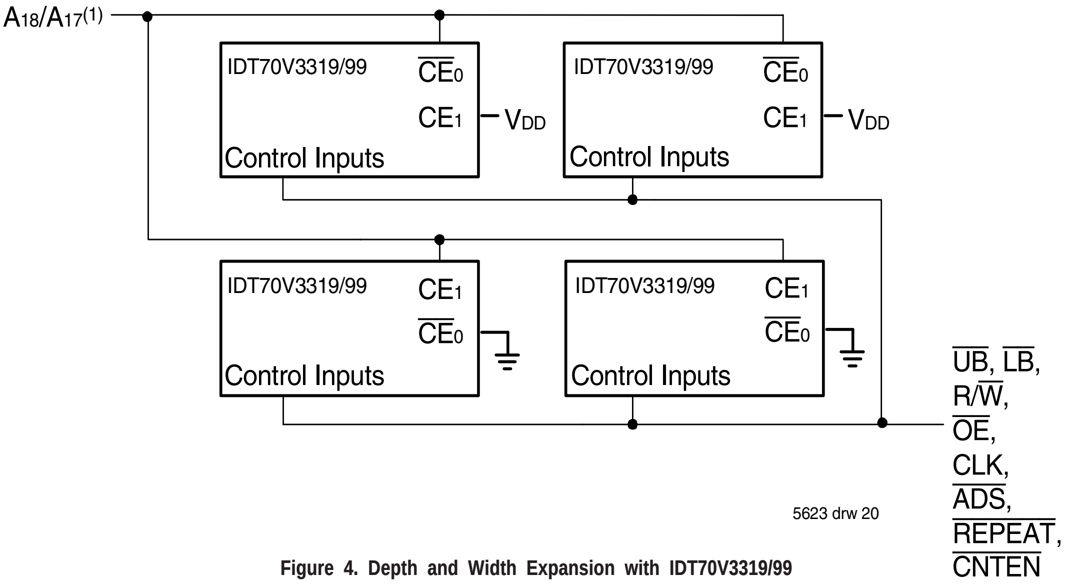


Figure 4. Depth and Width Expansion with IDT70V3319/99

NOTE:

1. A_{17} is for IDT70V3319, A_{16} is for IDT70V3399.

JTAG Timing Specifications

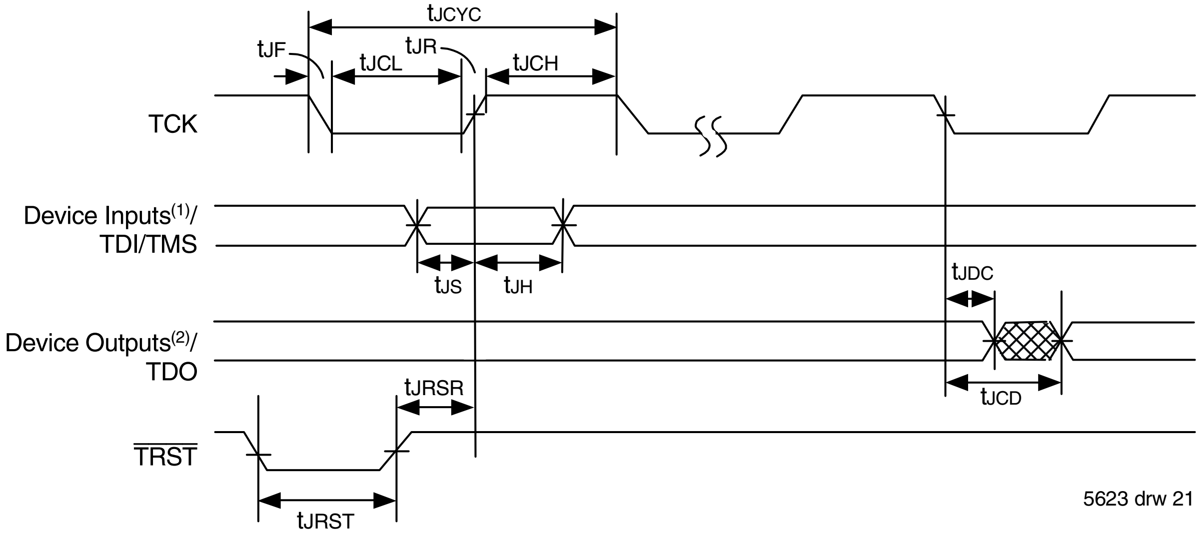


Figure 5. Standard JTAG Timing

NOTES:
1. Device inputs = All device inputs except TDI, TMS, and TRST.
2. Device outputs = All device outputs except TDO.

JTAG AC Electrical Characteristics(1,2,3,4)

Symbol	Parameter	70V3319/99		
		Min.	**Max.**	**Units**
tJCYC	JTAG Clock Input Period	100	—	ns
tJCH	JTAG Clock HIGH	40	—	ns
tJCL	JTAG Clock Low	40	—	ns
tJR	JTAG Clock Rise Time	—	3(1)	ns
tJF	JTAG Clock Fall Time	—	3(1)	ns
tJRST	JTAG Reset	50	—	ns
tJRSR	JTAG Reset Recovery	50	—	ns
tJCD	JTAG Data Output	—	25	ns
tJDC	JTAG Data Output Hold	0	—	ns
tJS	JTAG Setup	15	—	ns
tJH	JTAG Hold	15	—	ns

5623 tbl 12

NOTES:
1. Guaranteed by design.
2. 30pF loading on external output signals.
3. Refer to AC Electrical Test Conditions stated earlier in this document.
4. JTAG operations occur at one speed (10MHz). The base device may run at any speed specified in this datasheet.

Identification Register Definitions

Instruction Field	Value	Description
Revision Number (31:28)	0x0	Reserved for version number
IDT Device ID (27:12)	0x0314(1)	Defines IDT part number
IDT JEDEC ID (11:1)	0x33	Allows unique identification of device vendor as IDT
ID Register Indicator Bit (Bit 0)	1	Indicates the presence of an ID register

5623 tbl 13

NOTE:
1. Device ID for IDT70V3399 is 0x0315.

Scan Register Sizes

Register Name	Bit Size
Instruction (IR)	4
Bypass (BYR)	1
Identification (IDR)	32
Boundary Scan (BSR)	Note (3)

5623 tbl 14

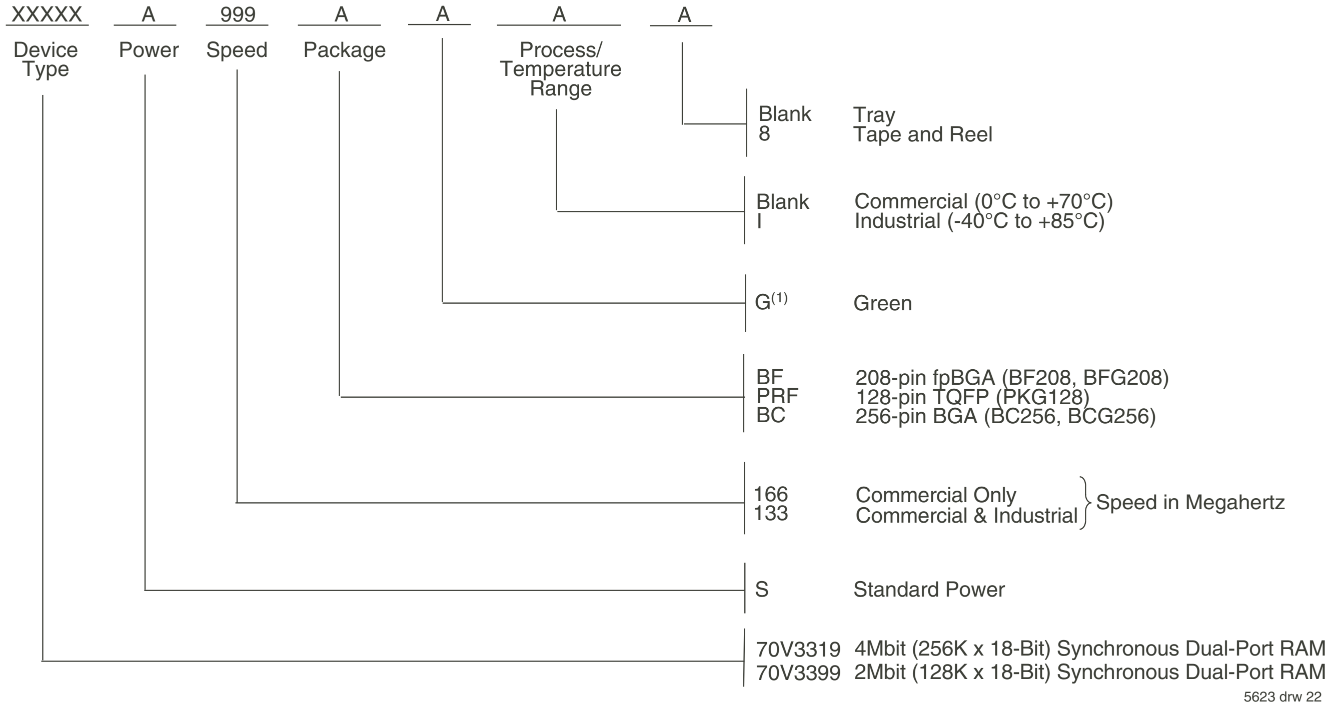
System Interface Parameters

Instruction	Code	Description
EXTEST	0000	Forces contents of the boundary scan cells onto the device outputs(1). Places the boundary scan register (BSR) between TDI and TDO.
BYPASS	1111	Places the bypass register (BYR) between TDI and TDO.
IDCODE	0010	Loads the ID register (IDR) with the vendor ID code and places the register between TDI and TDO.
HIGHZ	0011	Places the bypass register (BYR) between TDI and TDO. Forces all device output drivers to a High-Z state.
SAMPLE/PRELOAD	0001	Places the boundary scan register (BSR) between TDI and TDO. SAMPLE allows data from device inputs(2) to be captured in the boundary scan cells and shifted serially through TDO. PRELOAD allows data to be input serially into the boundary scan cells via the TDI.
RESERVED	All other codes	Several combinations are reserved. Do not use codes other than those identified above.

5623 tbl 15

NOTES:
1. Device outputs = All device outputs except TDO.
2. Device inputs = All device inputs except TDI, TMS, and $\overline{\text{TRST}}$.
3. The Boundary Scan Descriptive Language (BSDL) file for this device is available on the IDT website (www.idt.com), or by contacting your local IDT sales representative.

Ordering Information



NOTES:

1. Contact your local sales office for industrial temp. range for other speeds, packages and powers.
LEAD FINISH (SnPb) parts are Obsolete excluding BGA & fpBGA. Product Discontinuation Notice - PDN# SP-17-02
Note that information regarding recently obsoleted parts is included in this datasheet for customer convenience.

Orderable Part Information

Speed (MHz)	Orderable Part ID	Pkg. Code	Pkg. Type	Temp. Grade
133	70V3319S133BC	BC256	CABGA	C
	70V3319S133BC8	BC256	CABGA	C
	70V3319S133BCGI	BCG256	CABGA	I
	70V3319S133BCI	BC256	CABGA	I
	70V3319S133BCI8	BC256	CABGA	I
	70V3319S133BF	BF208	CABGA	C
	70V3319S133BF8	BF208	CABGA	C
	70V3319S133BFI	BF208	CABGA	I
	70V3319S133BFI8	BF208	CABGA	I
	70V3319S133PRFGI	PKG128	TQFP	I
	70V3319S133PRFGI8	PKG128	TQFP	I
166	70V3319S166BC	BC256	CABGA	C
	70V3319S166BC8	BC256	CABGA	C
	70V3319S166BCG	BCG256	CABGA	C
	70V3319S166BF	BF208	CABGA	C
	70V3319S166BF8	BF208	CABGA	C
	70V3319S166BFG	BFG208	CABGA	C
	70V3319S166BFG8	BFG208	CABGA	C
	70V3319S166PRFG	PKG128	TQFP	C
	70V3319S166PRFG8	PKG128	TQFP	C

Speed (MHz)	Orderable Part ID	Pkg. Code	Pkg. Type	Temp. Grade
133	70V3399S133BC	BC256	CABGA	C
	70V3399S133BC8	BC256	CABGA	C
	70V3399S133BCI	BC256	CABGA	I
	70V3399S133BCI8	BC256	CABGA	I
	70V3399S133BF	BF208	CABGA	C
	70V3399S133BF8	BF208	CABGA	C
	70V3399S133BFI	BF208	CABGA	I
	70V3399S133BFI8	BF208	CABGA	I
166	70V3399S166BC	BC256	CABGA	C
	70V3399S166BC8	BC256	CABGA	C
	70V3399S166BF	BF208	CABGA	C
	70V3399S166BF8	BF208	CABGA	C
	70V3399S166BFG	BFG208	CABGA	C
	70V3399S166BFG8	BFG208	CABGA	C

Datasheet Document History:

06/02/00:	Initial Public Offering
07/12/00:	Page 1 Added mux to functional block diagram
06/20/01:	Page 1 Added JTAG information for TQFP package
	Page 4 Corrected TQFP package size
07/30/01:	Page 1 Added PL/$\overline{FT}$option
	Page 20 Changed maximum value for JTAG AC Electrical Characteristics for t_{JCD} from 20ns to 25ns
	Page 9 Added Industrial Temperature DC Parameters
11/20/01:	Page 2, 3 & 4 Added date revision for pin configurations
	Page 11 Changed t_{OE} value in AC Electrical Characteristics, please refer to Errata #SMEN-01-05
	Page 1 & 22 Replaced TM logo with ® logo
	Page 10 Changed AC Test Conditions Input Rise/Fall Times
08/06/02:	Consolidated multiple devices into one datasheet
	Page 1 & 5 Added DCD capability for Pipelined Outputs
	Page 7 Clarified T_{BIAS} and added T_{JN}
	Page 9 Changed DC Electrical Parameters
	Page 11 Removed Clock Rise & Fall Time from AC Electrical Characteristics Table
	Removed Preliminary status
05/19/03:	Page 11 Added Byte Enable SetupTime & Byte Enable Hold Time to AC Electrical Characteristics Table
	Page 22 Added IDT Clock Solution Table
02/08/06:	Page 1 Added green availability to features
	Page 6 Changed footnote 2 for Truth Table I from $\overline{ADS}$, $\overline{CNTEN}$, $\overline{REPEAT}$ = V_{IH} to $\overline{ADS}$, $\overline{CNTEN}$, $\overline{REPEAT}$ = X
	Page 22 Added green indicator to ordering information
07/25/08:	Page 9 Corrected a typo in the DC Chars table
01/19/09:	Page 22 Removed "IDT" from orderable part number
10/03/14:	Page 22 Added Tape & Reel to the Ordering Information
06/20/18:	Product Discontinuation Notice - PDN# SP-17-02
	Last time buy expires June 15, 2018
09/12/19:	Page 2, 3 & 4 Updated package codes
	Page 22 Added Orderable Part Information table and removed IDT Clock Solution table
11/04/19:	Page 22 Corrected "ns" to "MHz" in the header of the Orderable Part Information tables

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